



ASE GROUP

日月光半導體 2018年 第一季 法人說明會

Advanced Semiconductor
Engineering, Inc.
Apr. 27, 2018



Safe Harbor Notice

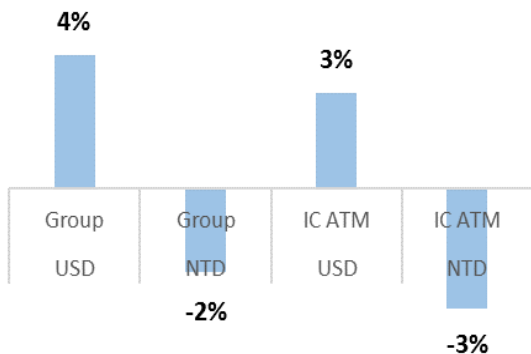
This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclical and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the uncertainties as to whether we can complete the share exchange contemplated by a joint share exchange agreement between Siliconware Precision Industries Co., Ltd. and us; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2017 Annual Report on Form 20-F filed on March 28, 2018.

匯率影響

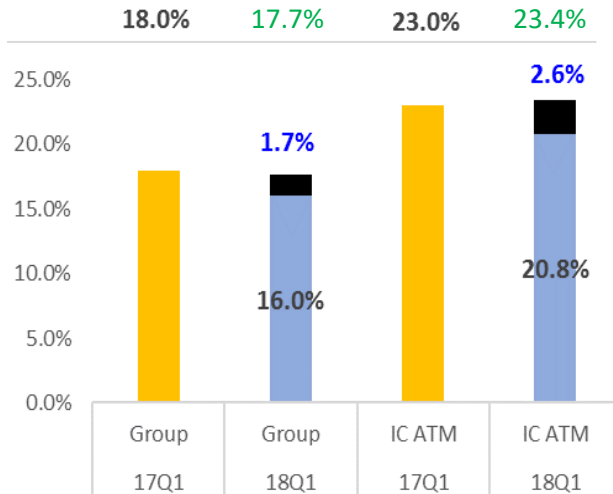
- 新台幣與美金匯率假設:

- 2017年第一季及2018年第一季 (31.20 vs. 29.33): 新台幣匯率相對美金升值6.0%

1Q18 Revenue Growth (YoY%)



Gross Margin by Sector



合併綜合損益表

(未經會計師查核)

(新台幣百萬元)	Q1 / 2018	%	Q4 / 2017	%	Q1 / 2017	%	季變化	年變化
營業收入淨額:								
封裝	29,368	45.2%	33,045	39.4%	29,806	44.8%	-11%	-1%
測試	5,679	8.7%	6,553	7.8%	6,365	9.6%	-13%	-11%
材料直接銷售	1,009	1.6%	922	1.1%	892	1.3%	9%	13%
電子代工服務	28,686	44.2%	43,285	51.5%	29,355	44.1%	-34%	-2%
其它	224	0.3%	181	0.2%	133	0.2%	24%	68%
營業收入淨額合計	64,966	100.0%	83,986	100.0%	66,551	100.0%	-23%	-2%
營業毛利	10,388	16.0%	14,793	17.6%	11,975	18.0%	-30%	-13%
營業淨利 (淨損)	4,316	6.6%	7,706	9.2%	5,225	7.9%	-44%	-17%
稅前淨利 (淨損)	3,776	5.8%	7,879	9.4%	3,845	5.8%	-52%	-2%
所得稅利益 (費用)	(1,420)	-2.2%	(1,085)	-1.3%	(886)	-1.3%		
非控制權益	(260)	-0.4%	(548)	-0.7%	(400)	-0.6%		
歸屬於本公司業主之淨利	2,096	3.2%	6,246	7.4%	2,559	3.8%	-66%	-18%
基本每股盈餘 (新台幣元)	0.25		0.74		0.33		-66%	-24%
稀釋每股盈餘 (新台幣元)	0.24		0.71		0.29		-66%	-17%
EBITDA	11,893	18.3%	16,147	19.2%	11,764	17.7%	-26%	1%

綜合損益表 – 半導體封裝測試

(未經會計師查核)

(新台幣百萬元)

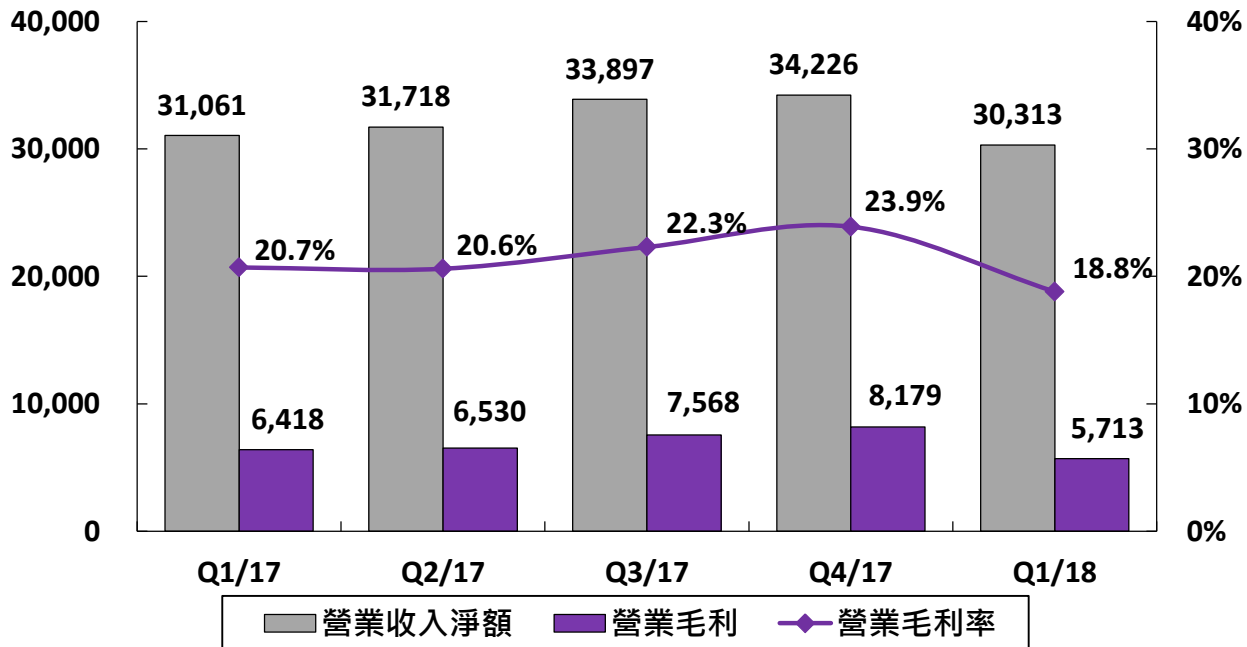
營業收入淨額:

	Q1 / 2018	%	Q4 / 2017	%	Q1 / 2017	%	季變化	年變化
封裝	30,313	81.8%	34,226	81.9%	31,061	80.9%	-11%	-2%
測試	5,679	15.3%	6,556	15.7%	6,365	16.6%	-13%	-11%
材料直接銷售	1,050	2.8%	989	2.4%	935	2.4%	6%	12%
其它	30	0.1%	23	0.0%	24	0.1%	30%	25%
營業收入淨額合計	37,072	100.0%	41,794	100.0%	38,385	100.0%	-11%	-3%
營業毛利	7,701	20.8%	10,862	26.0%	8,833	23.0%	-29%	-13%
營業淨利 (淨損)	3,418	9.2%	6,001	14.4%	3,983	10.4%	-43%	-14%
稅前淨利 (淨損)	3,401	9.2%	7,099	17.0%	3,207	8.4%	-52%	6%
所得稅利益 (費用)	(1,250)	-3.4%	(776)	-1.9%	(570)	-1.5%		
非控制權益	(55)	-0.1%	(77)	-0.2%	(78)	-0.2%		
歸屬於本公司業主之淨利	2,096	5.7%	6,246	14.9%	2,559	6.7%	-66%	-18%
EBITDA	10,393	28.0%	13,508	32.3%	9,800	25.5%	-23%	6%

封裝業務

(未經會計師查核)

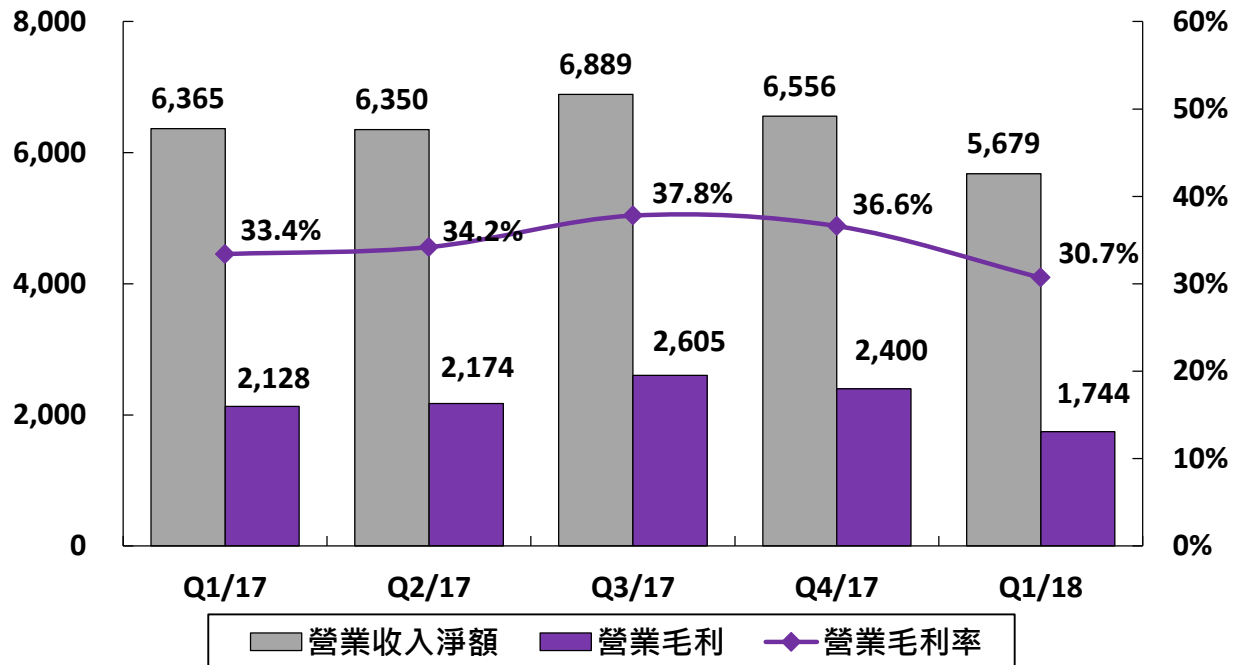
新台幣百萬元



測試業務

(未經會計師查核)

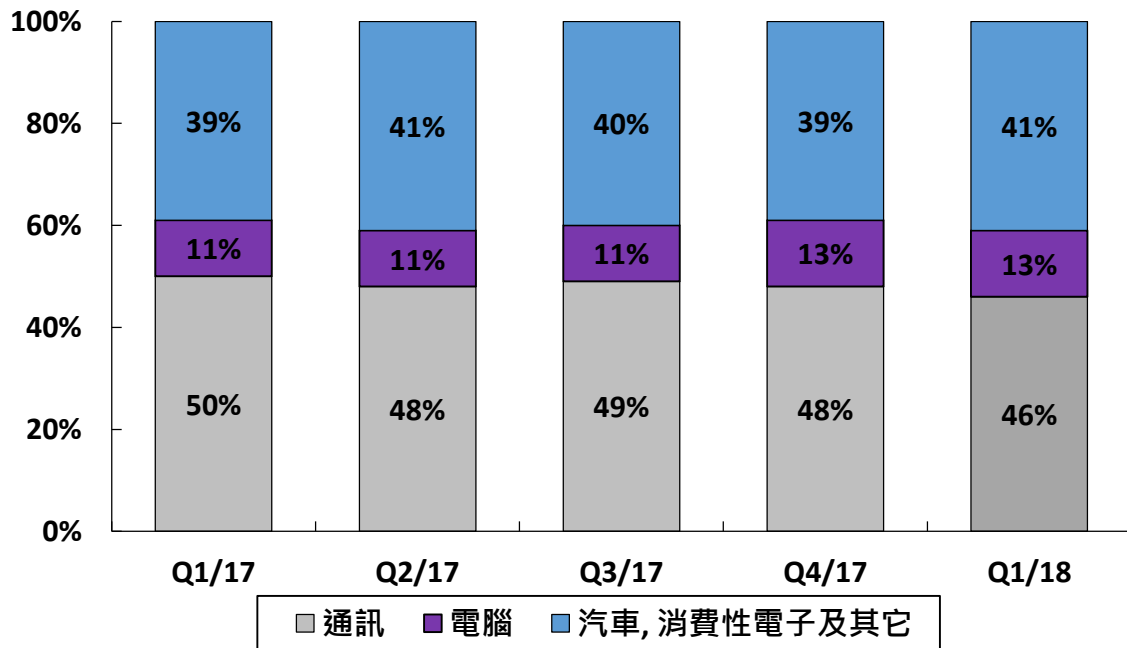
新台幣百萬元



半導體封測營收

產品應用別佔比

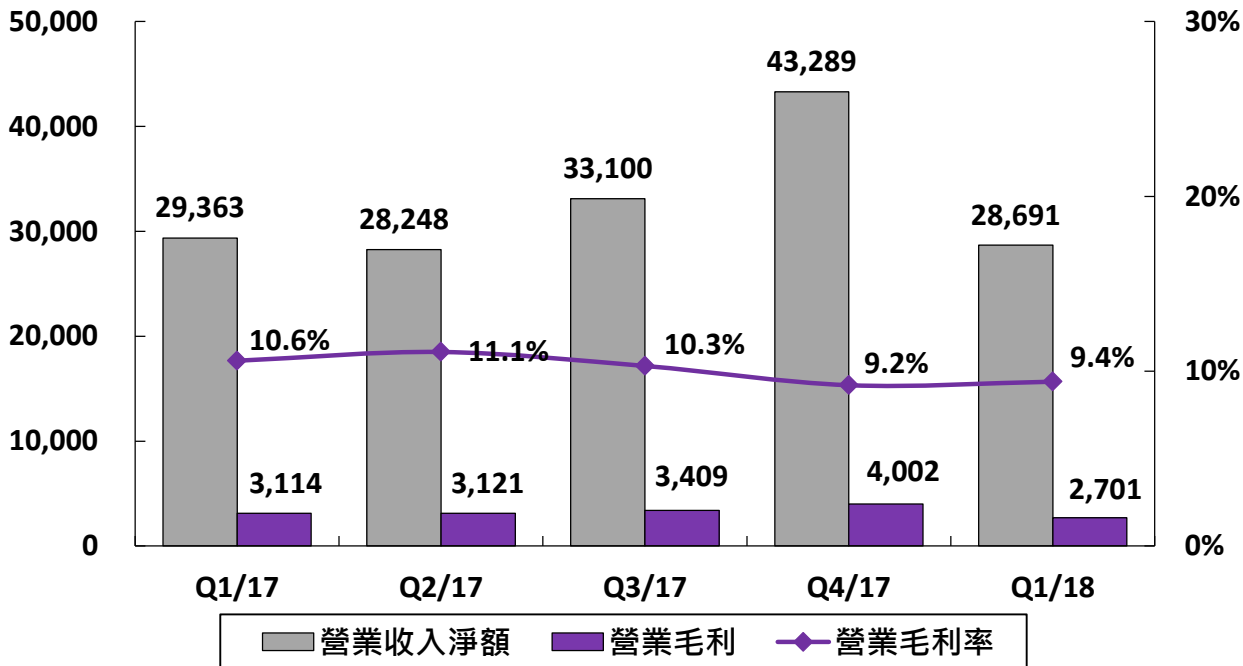
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電子代工服務業務

(未經會計師查核)

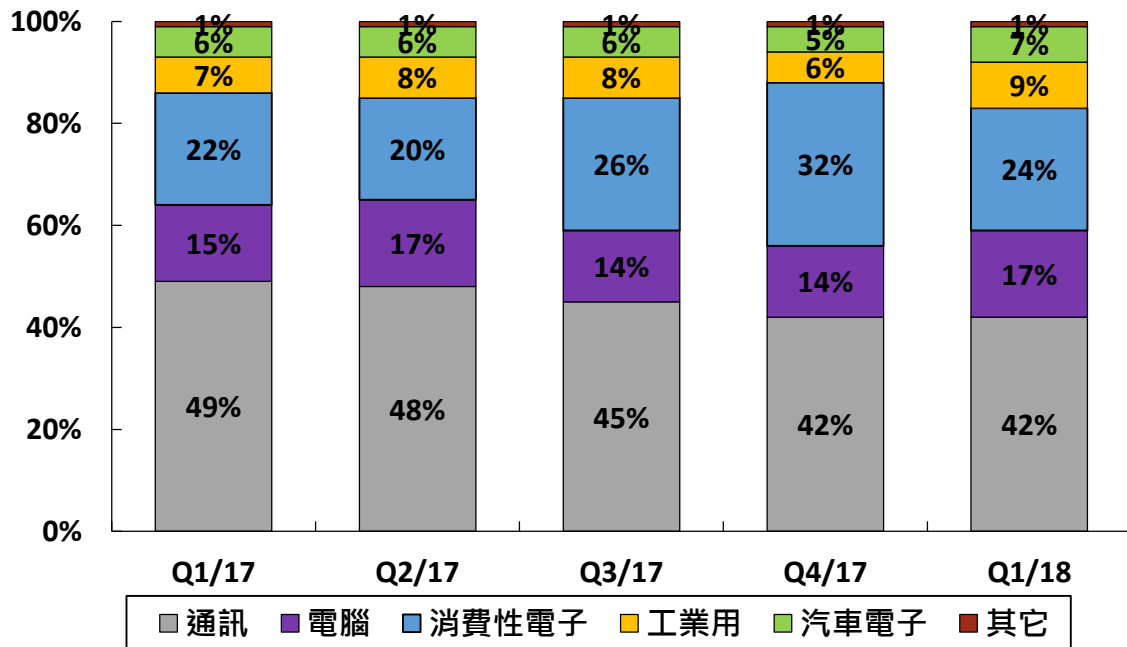
新台幣百萬元



電子代工服務業務

產品應用別

(未經會計師查核)



重要資產負債表項目及財務指標

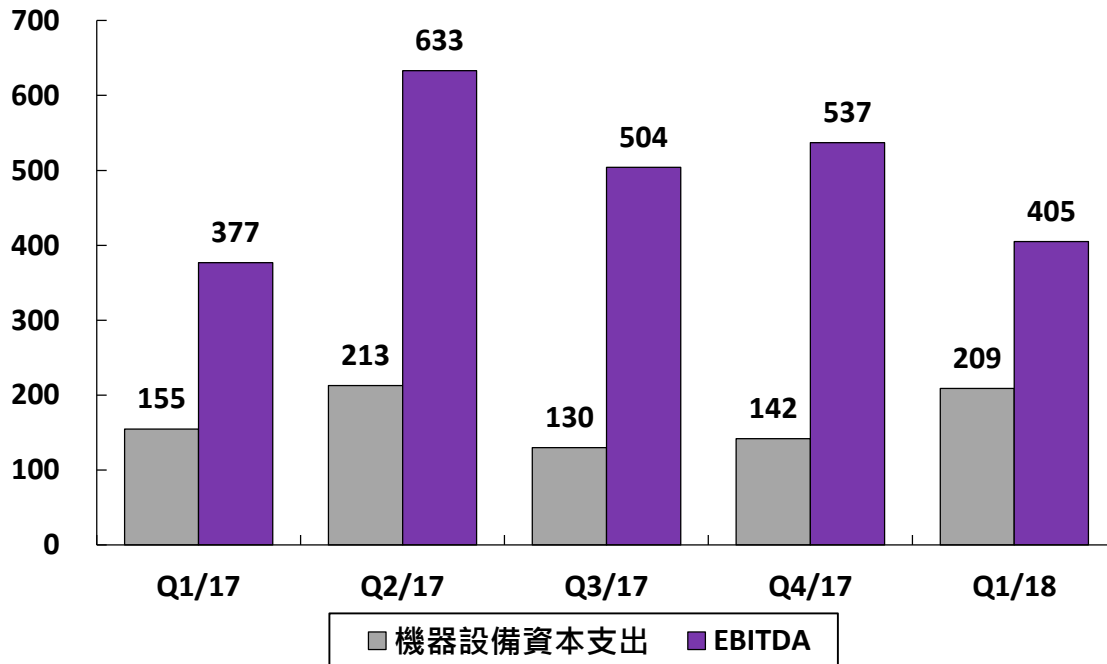
(未經會計師查核)

(新台幣百萬元)	2018年3月31日	2017年12月31日
現金及約當現金	43,146	46,078
金融資產 - 流動	10,551	5,785
金融資產 - 非流動及採用權益法之投資	50,854	50,983
不動產、廠房及設備	134,637	135,169
資產總計	356,880	363,858
短期借款及應付短期票券	17,381	17,962
一年內到期之應付公司債	0	6,161
一年內到期之長期借款及應付租賃款	5,739	8,280
應付公司債	16,983	16,982
長期借款及應付租賃款	34,435	27,520
權益總計 (含非控制權益)	206,027	204,001
當季 EBITDA	11,893	16,147
流動比率	1.55	1.37
負債權益比率	0.09	0.12

機器設備資本支出及EBITDA

(未經會計師查核)

美金百萬元



2018年第二季業績展望

根據對當前業務狀況的評估及匯率的假設，日月光公司2018年第二季的業績展望如下：

- 以美元計價之半導體封測事業第二季生意量將高於去年第二季，但低於去年第四季水準；
- 排除匯率影響，半導體封測事業第二季毛利率將約當於去年第二季水準；
- 電子代工服務第二季生意量將介於去年第二季與第三季之間；
- 電子代工服務第二季毛利率將略高於今年第一季毛利率。

Thank You

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